

## MRI600.17-E

### 2 in 1 IGBT Modules

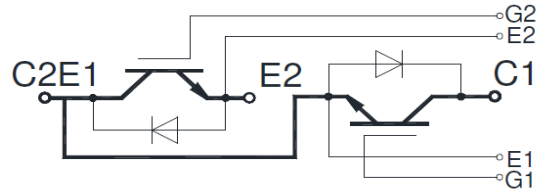


#### Features:

- Low  $V_{CEsat}$
- Standard housing
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

#### Typical applications:

- AC motor control
- Inverter and power supplies
- Motion/servo control
- Photovoltaic/Fuel cell
- Uninterruptible Power Supply System



Symbol	Characteristics	Test Conditions	Value			Unit
			Min	Typ	Max	
$V_{CES}$	Collector-Emitter voltage	$T_j = 25^\circ\text{C}$			1700	V
$V_{GES}$	Gate-Emitter voltage	$T_j = 25^\circ\text{C}$			$\pm 20$	V
$I_C$	Collector current	Continuous @ $T_c = 100^\circ\text{C}$			600	A
$I_{CM}$	Repetive peak collector current	$T_p = 1\text{ ms}$			1200	A
$P_C$	Collector power dissipation	$T_j = 175^\circ\text{C}$ , 1 device			4166	W
$T_j$	Junction temperature	/	-40		175	$^\circ\text{C}$
$T_{stg}$	Storage temperature	/	-40		125	$^\circ\text{C}$
$V_{ISO}$	Isolation between terminal and copper base	$T_j = 25^\circ\text{C}$ , AC: 1 minute	4000			V
Screw torque	Mounting (M5)	/	3.0		6.0	N·m
	Terminals (M6)	/	3.0		6.0	N·m
$I_{CES}$	Zero gate voltage collector current	$T_j = 25^\circ\text{C}$ , $V_{CE} = V_{CES}$ , $V_{GE} = 0\text{V}$			5.0	mA
$I_{GES}$	Gate-Emitter leakage current	$T_j = 25^\circ\text{C}$ , $V_{CE} = 0\text{V}$ , $V_{GE} = \pm 20\text{V}$			400	nA
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j = 25^\circ\text{C}$ , $V_{CE} = 20\text{V}$ , $I_C = 12\text{mA}$	5.6	6.2	6.8	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j = 25^\circ\text{C}$ , $V_{GE} = 15\text{V}$ , $I_C = 600\text{A}$		1.85	2.20	V
		$T_j = 125^\circ\text{C}$ , $V_{GE} = 15\text{V}$ , $I_C = 600\text{A}$		2.25		V
		$T_j = 150^\circ\text{C}$ , $V_{GE} = 15\text{V}$ , $I_C = 600\text{A}$		2.35		V
$Q_G$	Gate charge	$V_{GE} = \pm 15\text{V}$		4.50		$\mu\text{C}$
$R_{Gint}$	Internal gate resistor	$T_j = 25^\circ\text{C}$		1.30		$\Omega$
$C_{ies}$	Input capacitance	$T_j = 25^\circ\text{C}$ , $V_{CE} = 10\text{V}$ , $V_{GE} = 0\text{V}$ , $f = 1\text{MHz}$		45.9		nF
$C_{res}$	Reverse transfer capacitance			1.4		nF
$t_{on}$	Turn-on time	$T_j = 150^\circ\text{C}$ , $V_{CC} = 900\text{V}$ , $I_C = 600\text{A}$ , $V_{GE} = \pm 15\text{V}$ , $R_G = 1.0\Omega$ , inductive load		192		ns
$t_r$				80		ns
$t_{off}$				640		ns
$t_f$				216		ns
$E_{on}$	Turn-on energy loss per pulse	$T_j = 150^\circ\text{C}$ , $V_{CC} = 900\text{V}$ , $I_C = 600\text{A}$ , $V_{GE} = \pm 15\text{V}$ , $R_G = 1.0\Omega$ , inductive load		259		mJ
$E_{off}$	Turn-off energy loss per pulse			215		mJ
$I_{SC}$	Short circuit	$V_{CC} = 1000\text{V}$ , $V_{GE} = 15\text{V}$ , $T_j = 150^\circ\text{C}$ , $V_{CEM} = \leq 1700\text{V}$		2300		A
$t_{SC}$	Short circuit withstand time	$T_j = 150^\circ\text{C}$ , $V_{CC} = 720\text{V}$ , $V_{GE} = \pm 15\text{V}$ , $R_G = 7.5\Omega$	10			$\mu\text{s}$

Symbol	Characteristics	Test Conditions	Value			Unit
			Min	Typ	Max	
$V_F$	Forward on voltage	$T_j = 25^\circ\text{C}, I_F = 600\text{A}, V_{GE} = 0\text{V}$		1.80	2.25	V
		$T_j = 125^\circ\text{C}, I_F = 600\text{A}, V_{GE} = 0\text{V}$		1.95		V
		$T_j = 150^\circ\text{C}, I_F = 600\text{A}, V_{GE} = 0\text{V}$		1.90		V
$I_{RM}$	Peak reverse recovery current			670		A
$Q_R$	Recovery charge	$I_F = 600\text{A}, -di/dt = 7475\text{ A}/\mu\text{s}, V_R = 900\text{V}, V_{GE} = -15\text{V}, T_j = 150^\circ\text{C}$		314		$\mu\text{C}$
$E_{rec}$	Reverse recovery energy			198		mJ
$t_{rr}$	Reverse recovery time	$T_j = 150^\circ\text{C}, I_F = 600\text{A}$		1160		ns
$R_{th(j-c)}$	Thermal resistance (1 device)	IGBT			0.036	$^\circ\text{C}/\text{W}$
		FWD			0.128	$^\circ\text{C}/\text{W}$
$R_{th(c-f)}$	Contact thermal resistance (1 device)	with thermal compound		0.009		$^\circ\text{C}/\text{W}$
$R_{25}$	Rated resistance	$T_{VJ} = 25^\circ\text{C}$		5.0		k $\Omega$
$\Delta R/R$	Deviation of R100	$T_c = 100^\circ\text{C}, R_{100} = 493.3\Omega$	-5		5	%
$P_{25}$	Power dissipation	Continuous @ $T_c = 100^\circ\text{C}$			20.0	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50} (1/T_2 - 1/(298,15\text{ K}))]$		3375		K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80} (1/T_2 - 1/(298,15\text{ K}))]$		3411		K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100} (1/T_2 - 1/(298,15\text{ K}))]$		3433		K
$W_t$	Weight				350	g
Outline	465H3P					

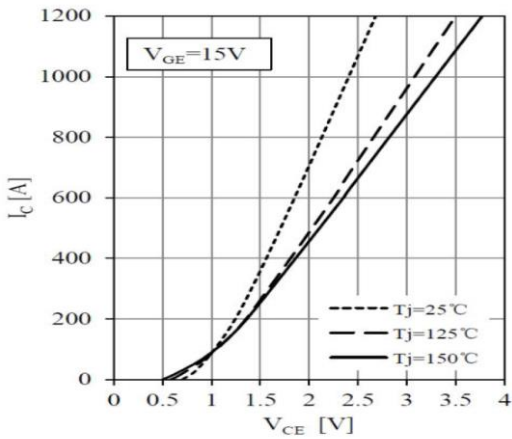


Fig 1. IGBT Output Characteristics

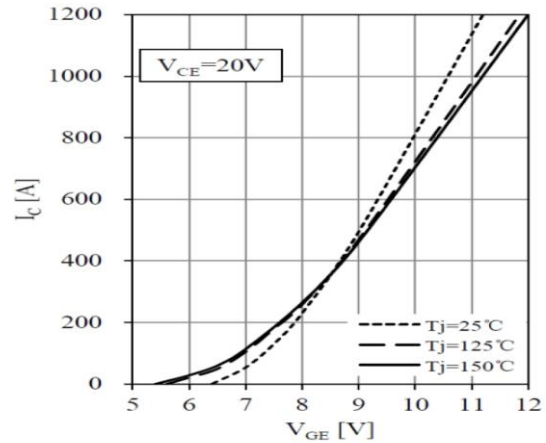


Fig 2. IGBT Transfer Characteristics

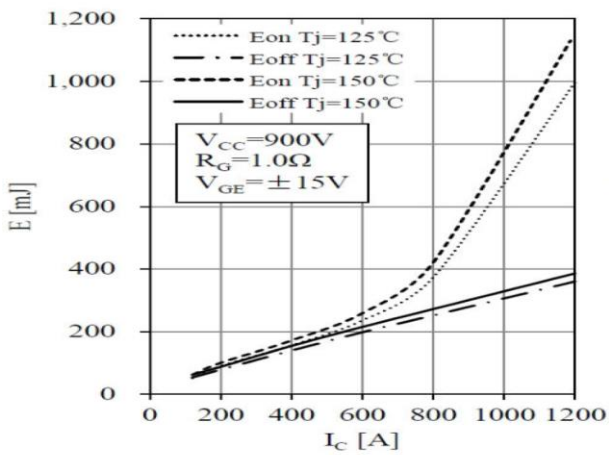


Fig 3. IGBT Switching Loss vs.  $I_c$

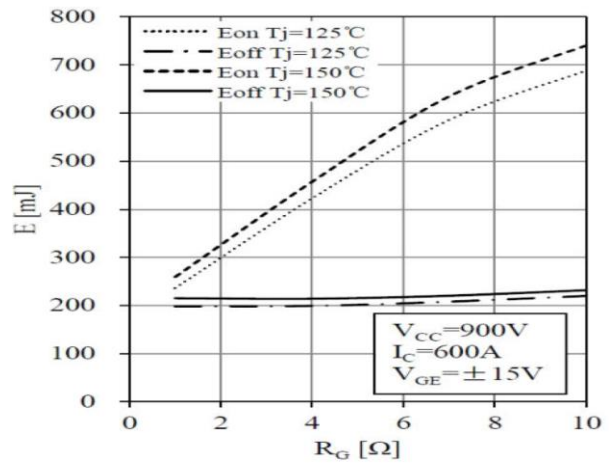


Fig 4. IGBT Switching Loss vs.  $R_G$

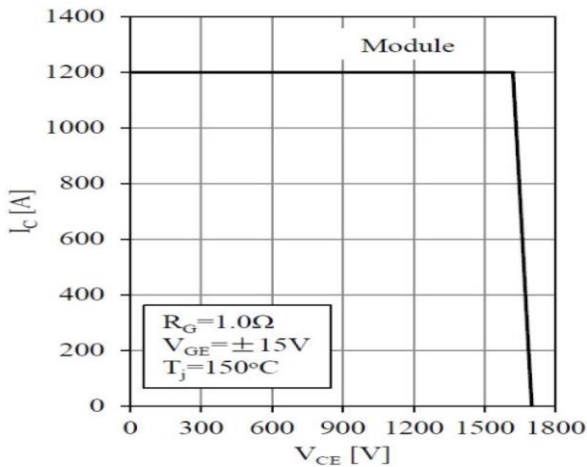


Fig 5. RBSOA

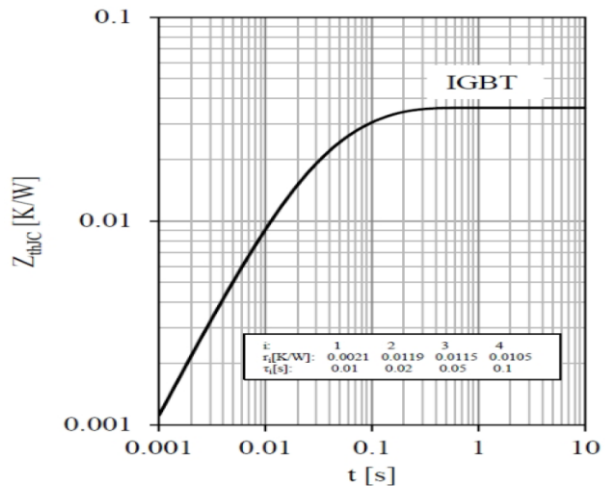


Fig 6. IGBT Transient Thermal Impedance

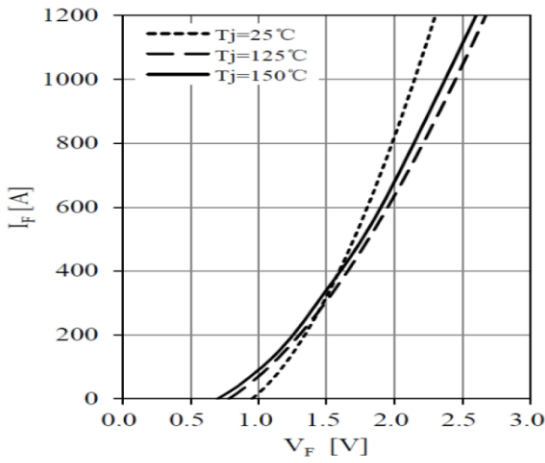


Fig 7. Diode Forward Characteristics

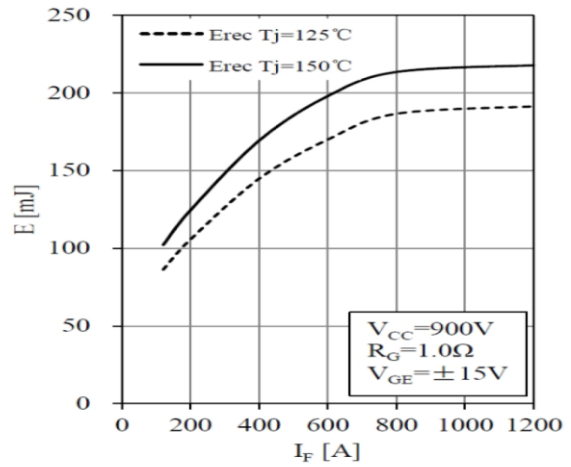


Fig 8. Diode Switching Loss vs.  $I_F$

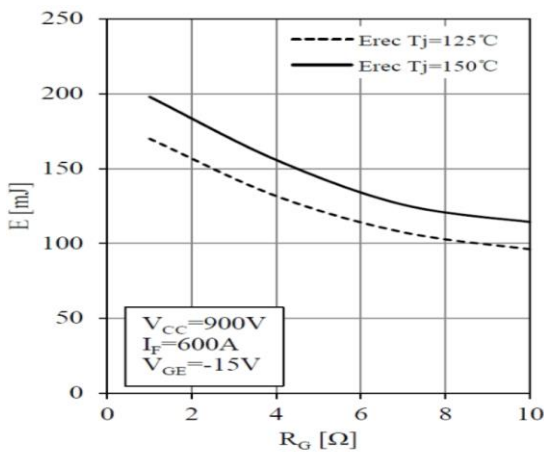


Fig 9. Diode Switching Loss vs.  $R_G$

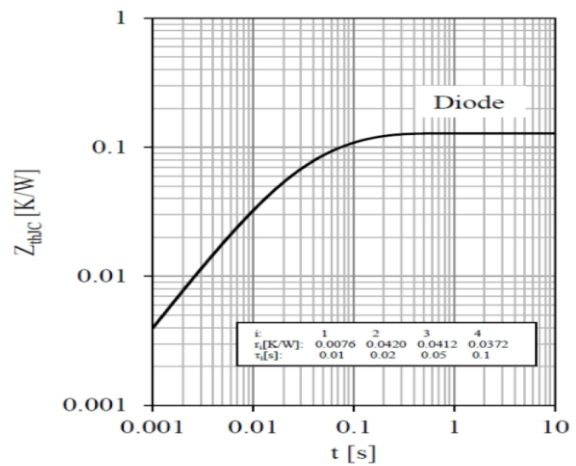


Fig 10. Diode Transient Thermal Impedance

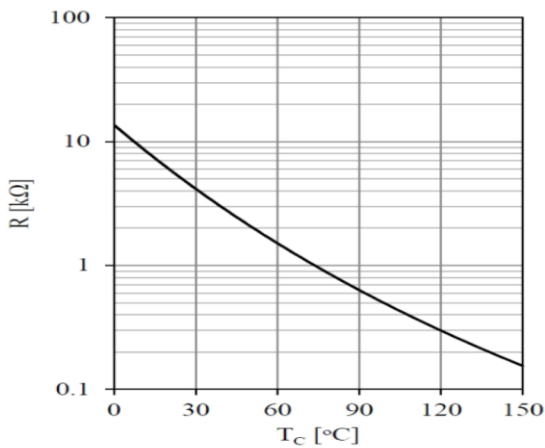


Fig 11. NTC Temperature Characteristic

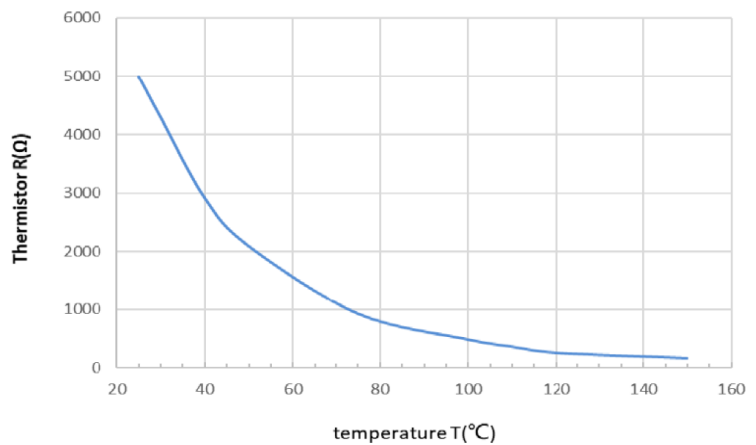
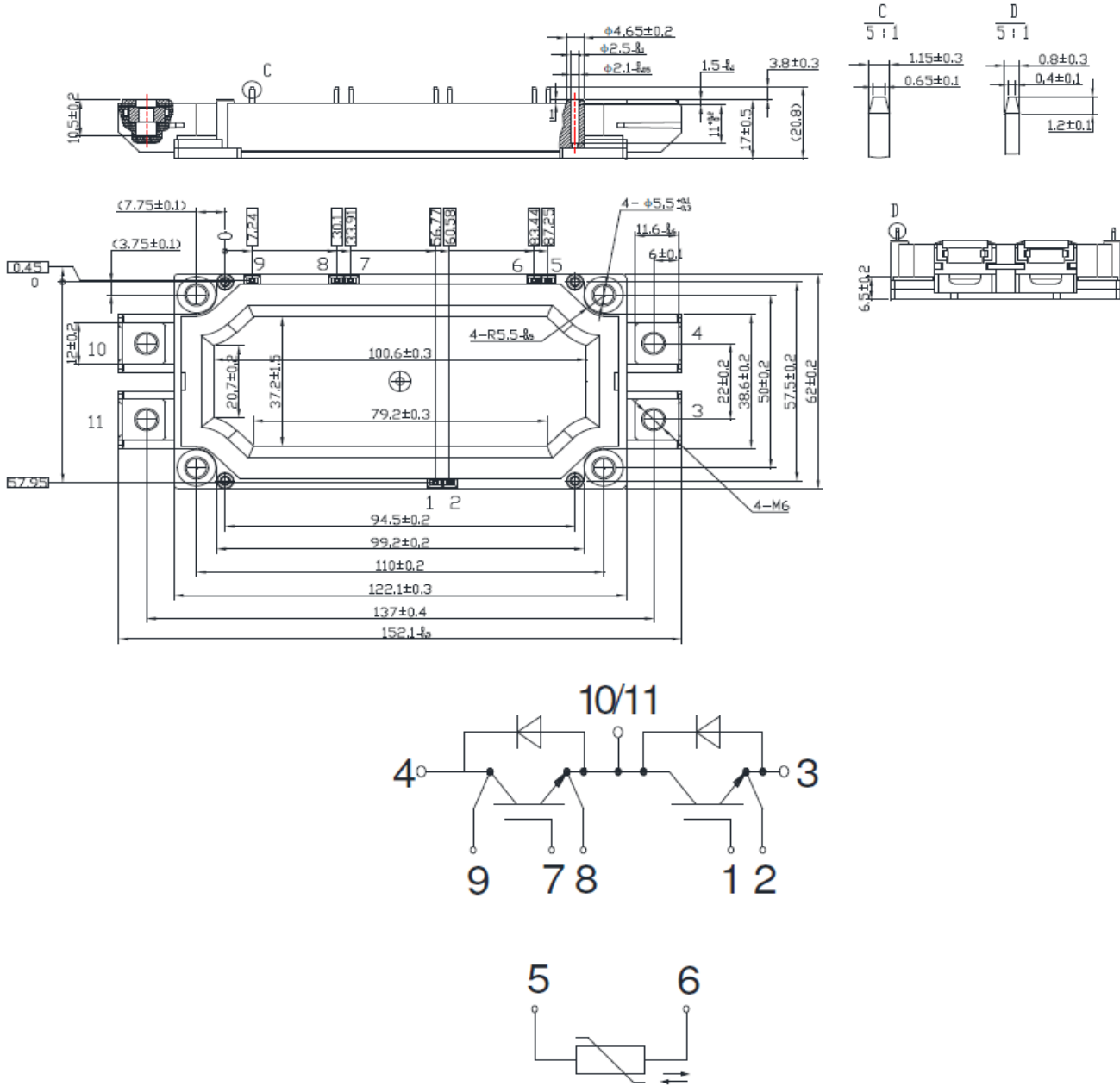


Fig 12. Thermistor Vs. temperature

### Outline:



(dimensions in mm)

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